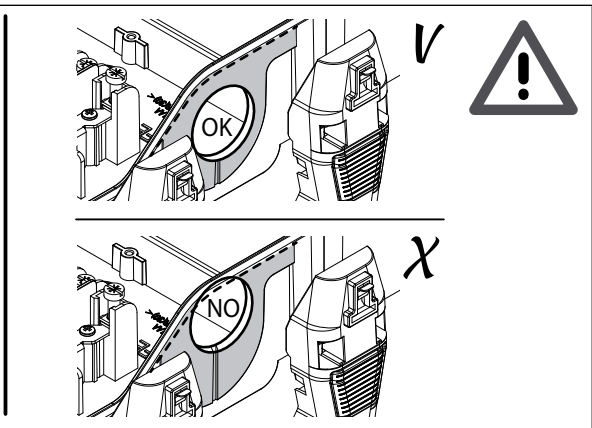
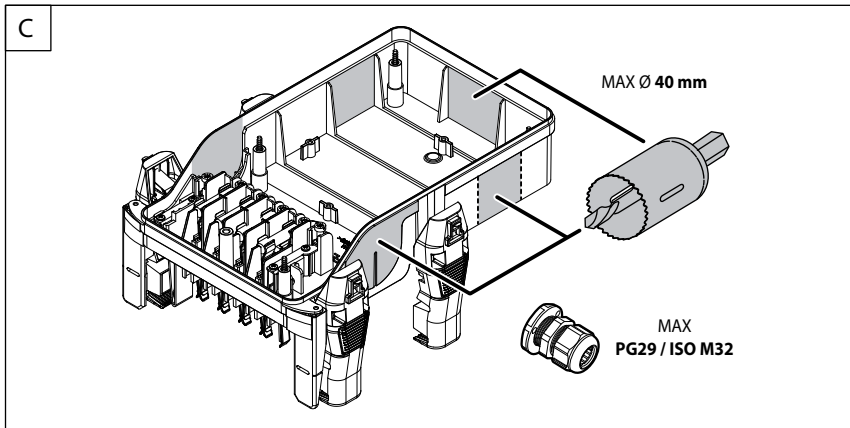
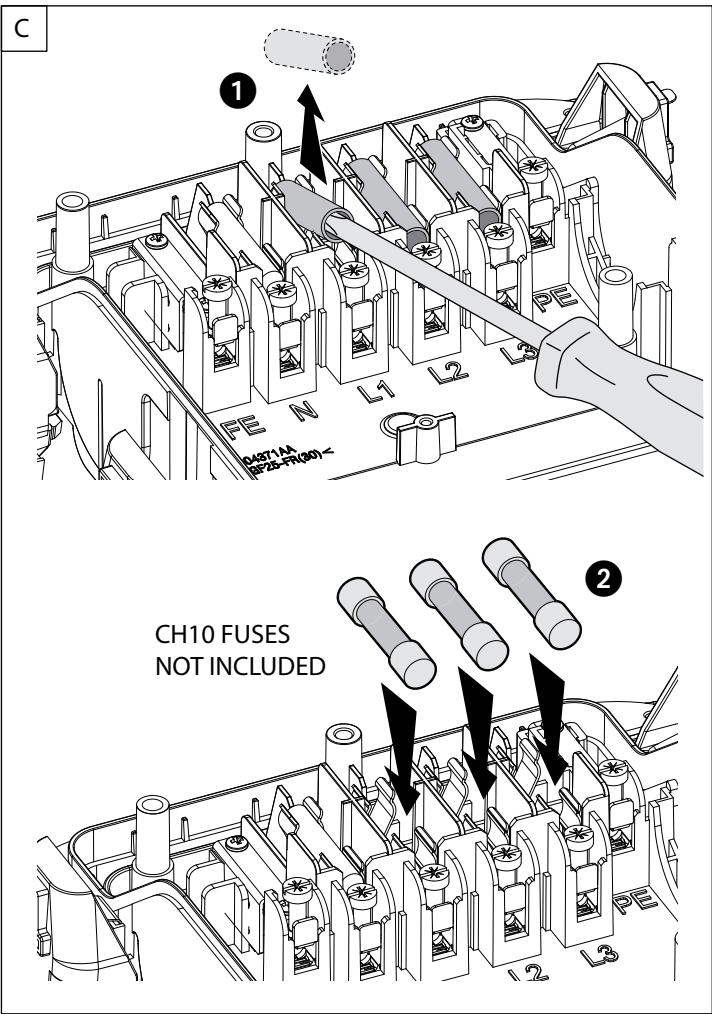
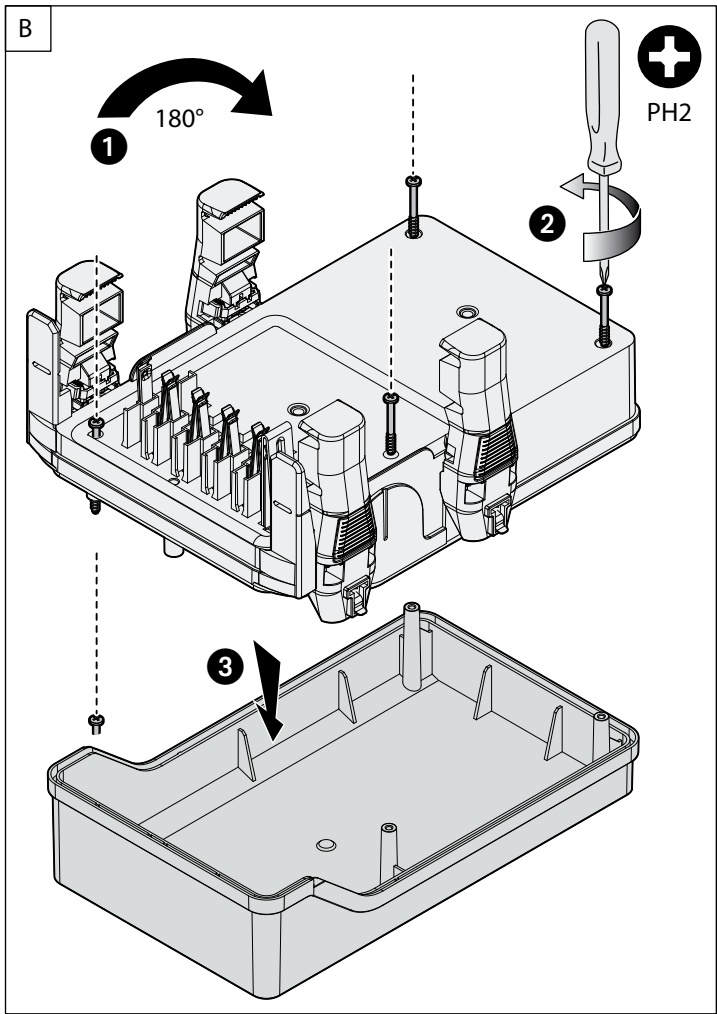
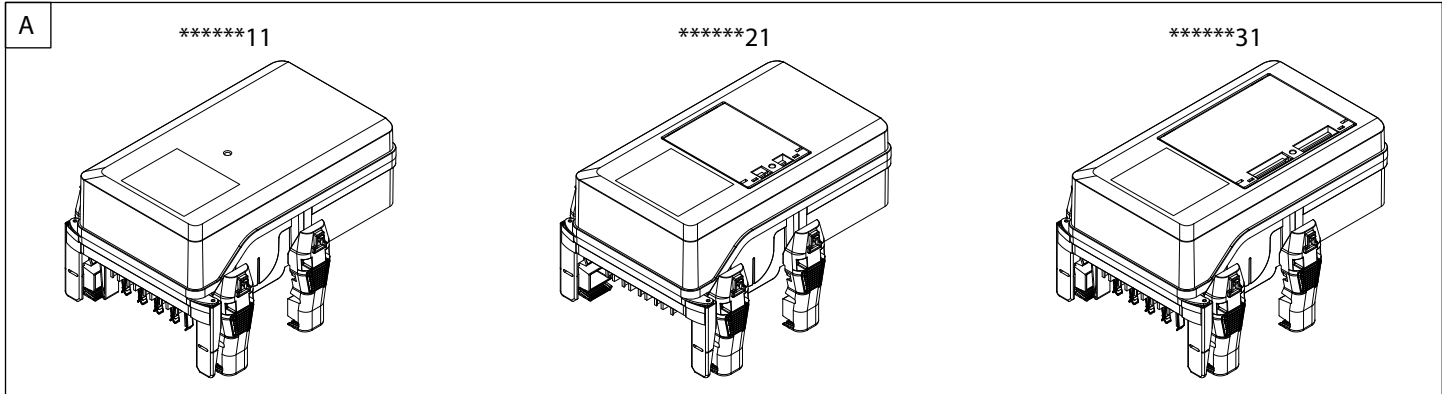
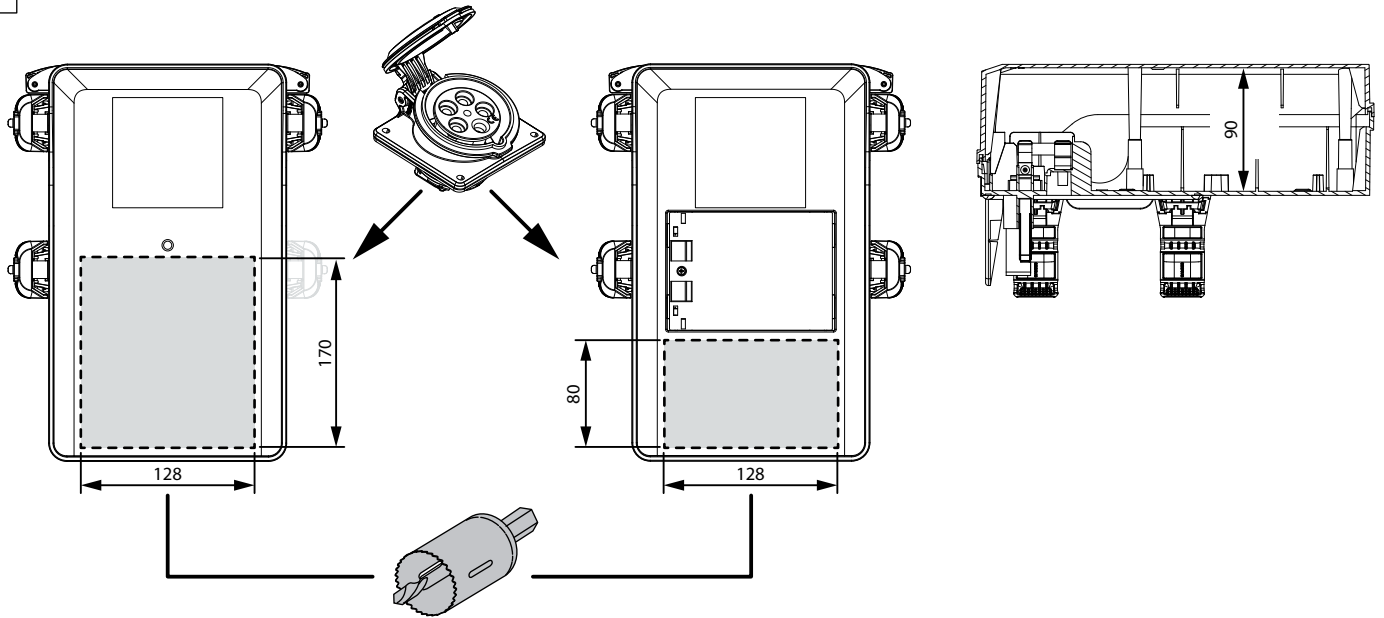
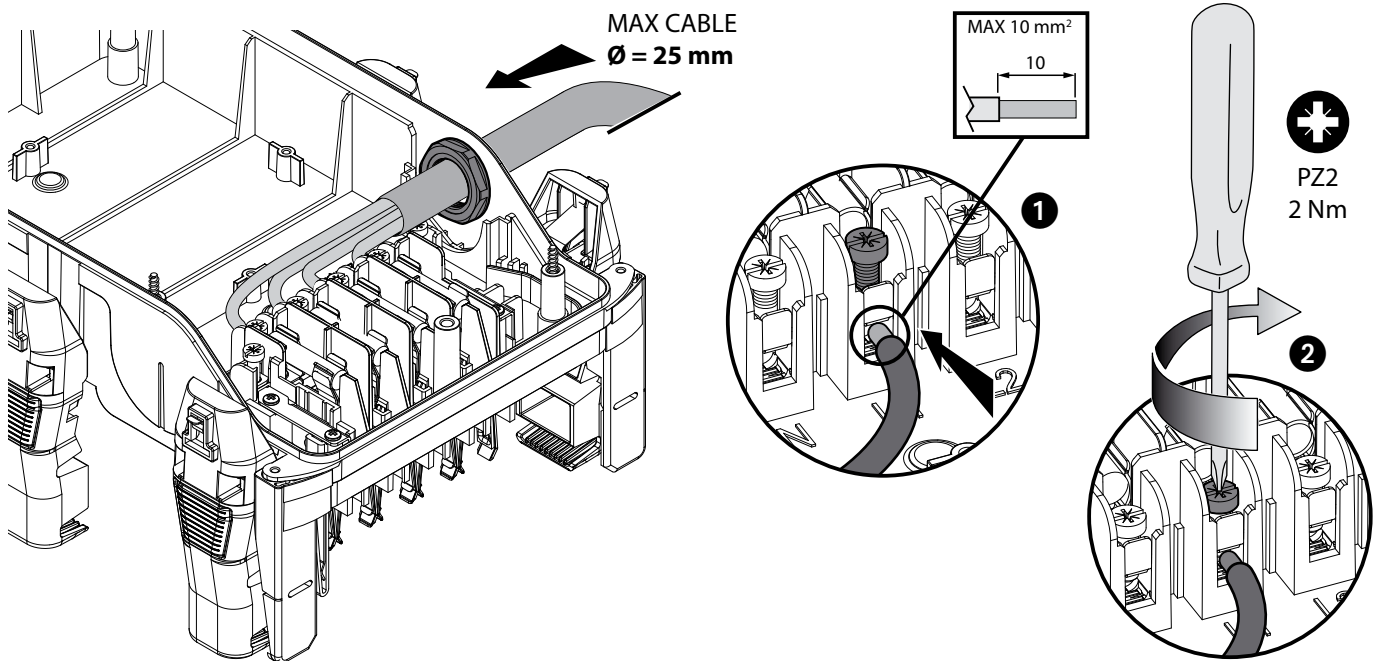




E

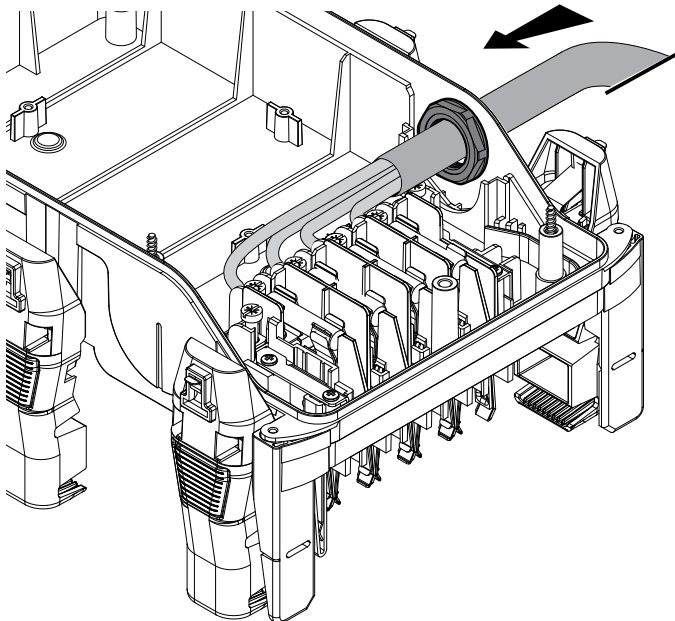


F

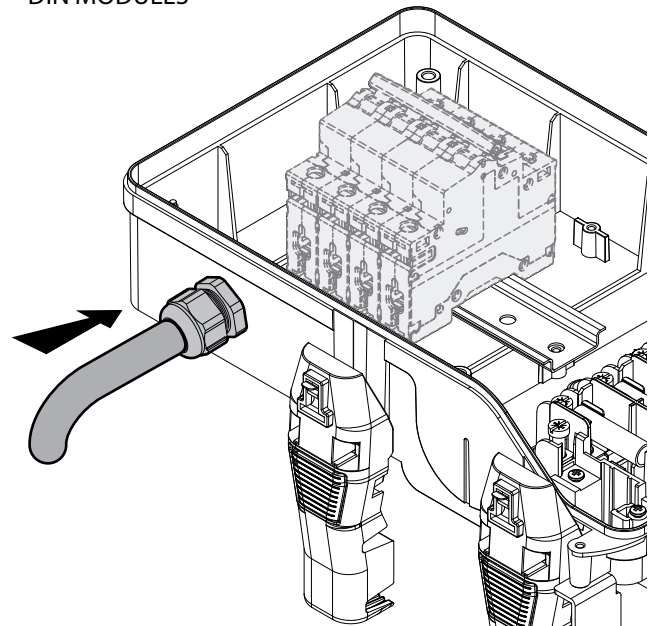


G

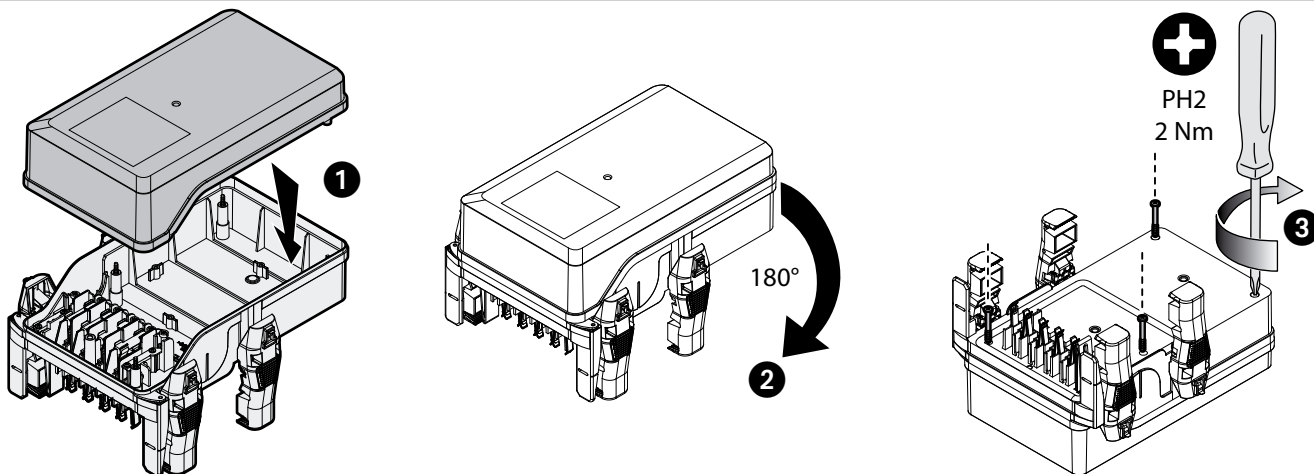
EMPTY



DIN MODULES



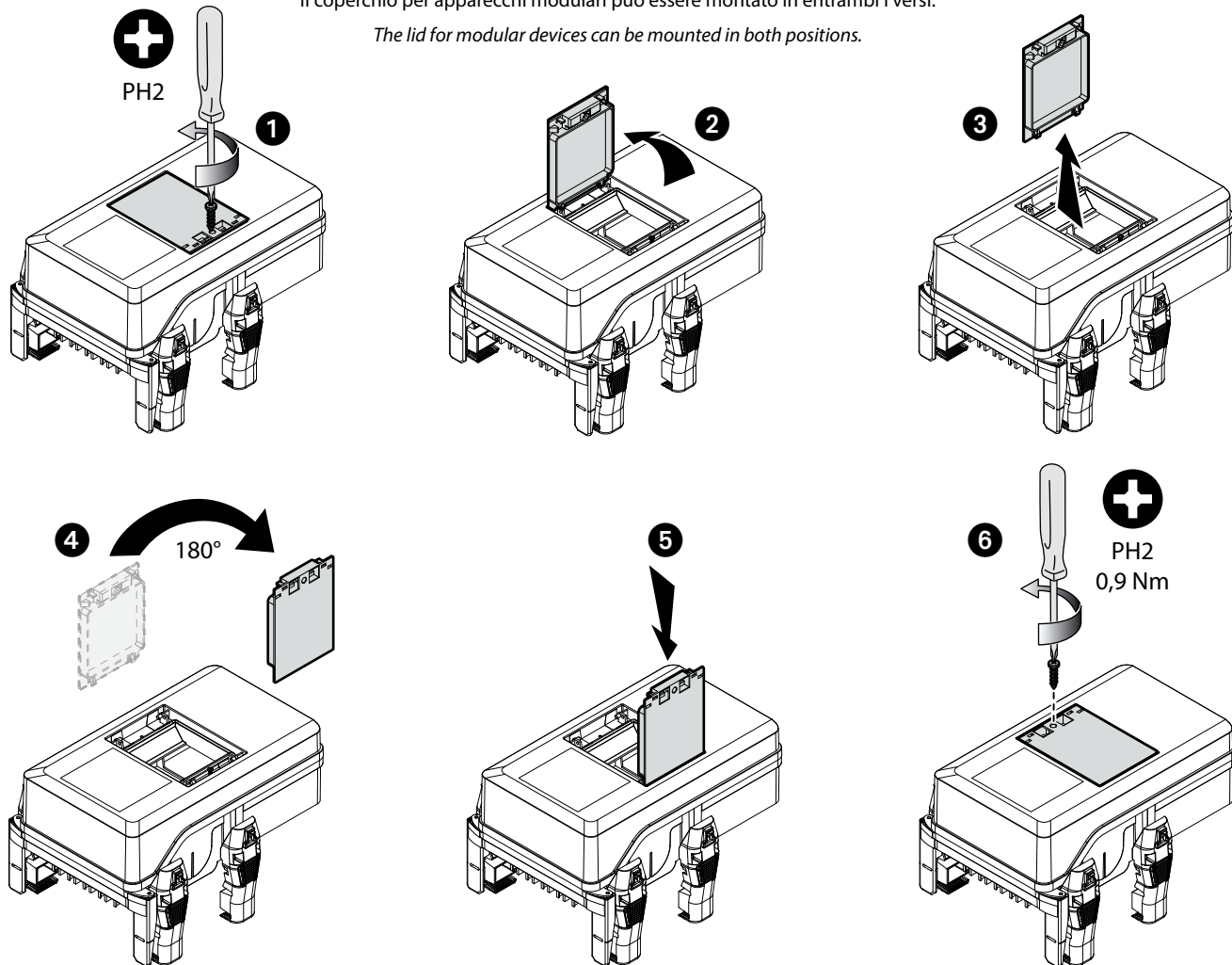
H



I

Il coperchio per apparecchi modulari può essere montato in entrambi i versi.

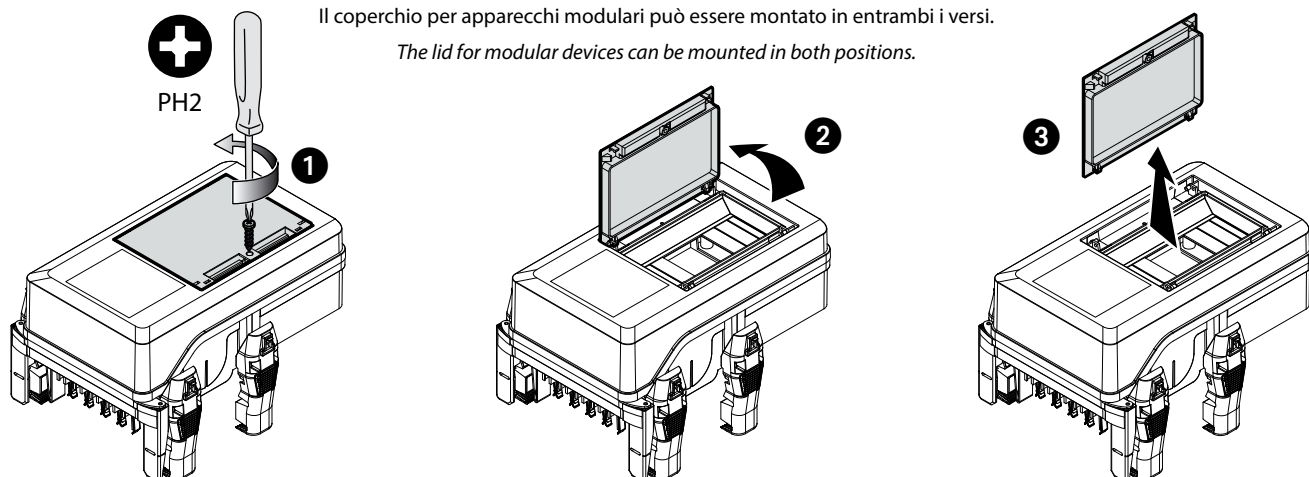
The lid for modular devices can be mounted in both positions.



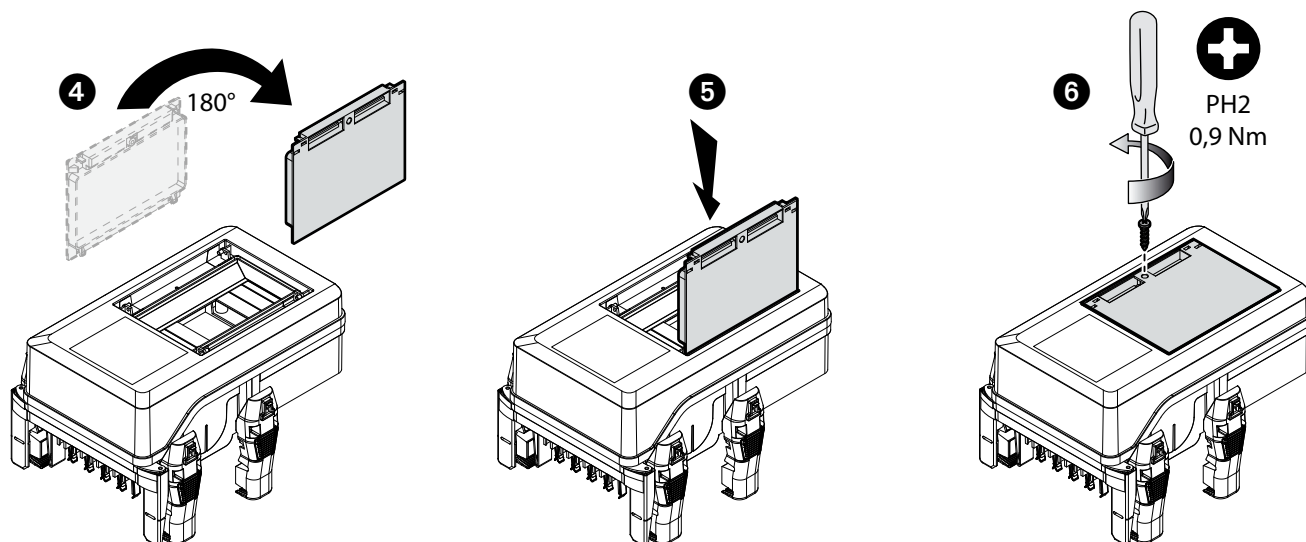
L

Il coperchio per apparecchi modulari può essere montato in entrambi i versi.

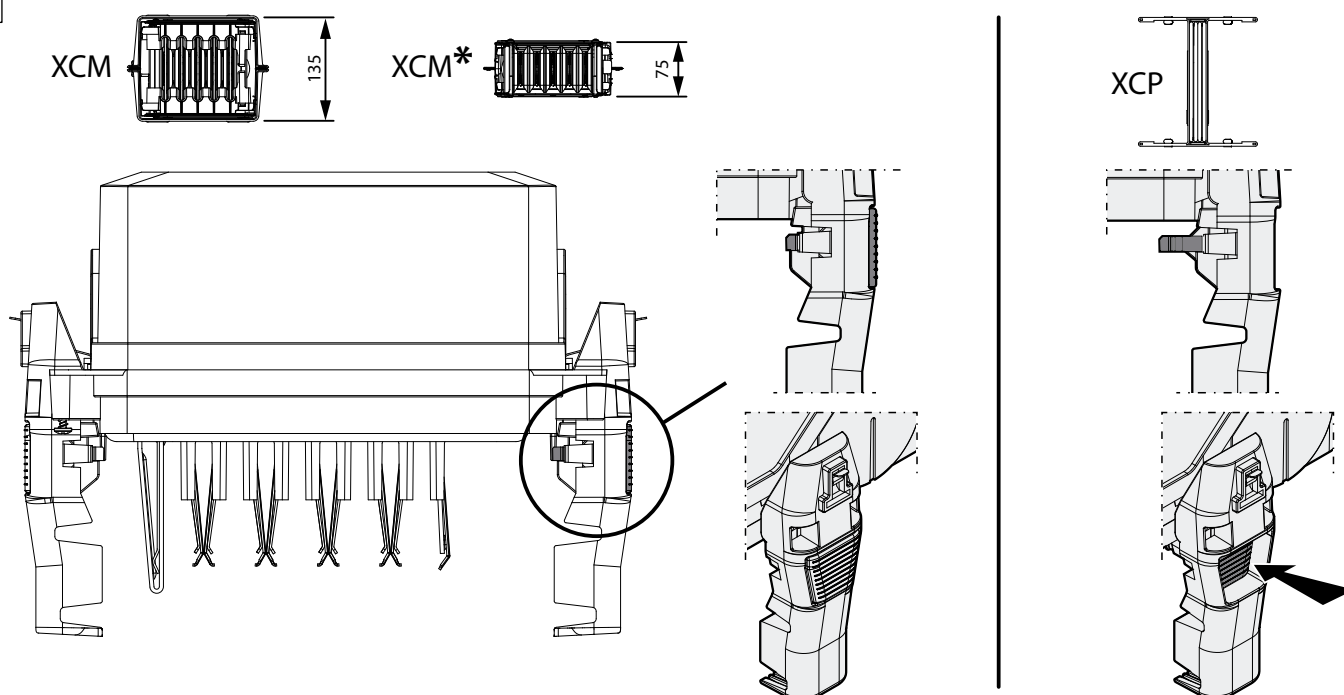
The lid for modular devices can be mounted in both positions.



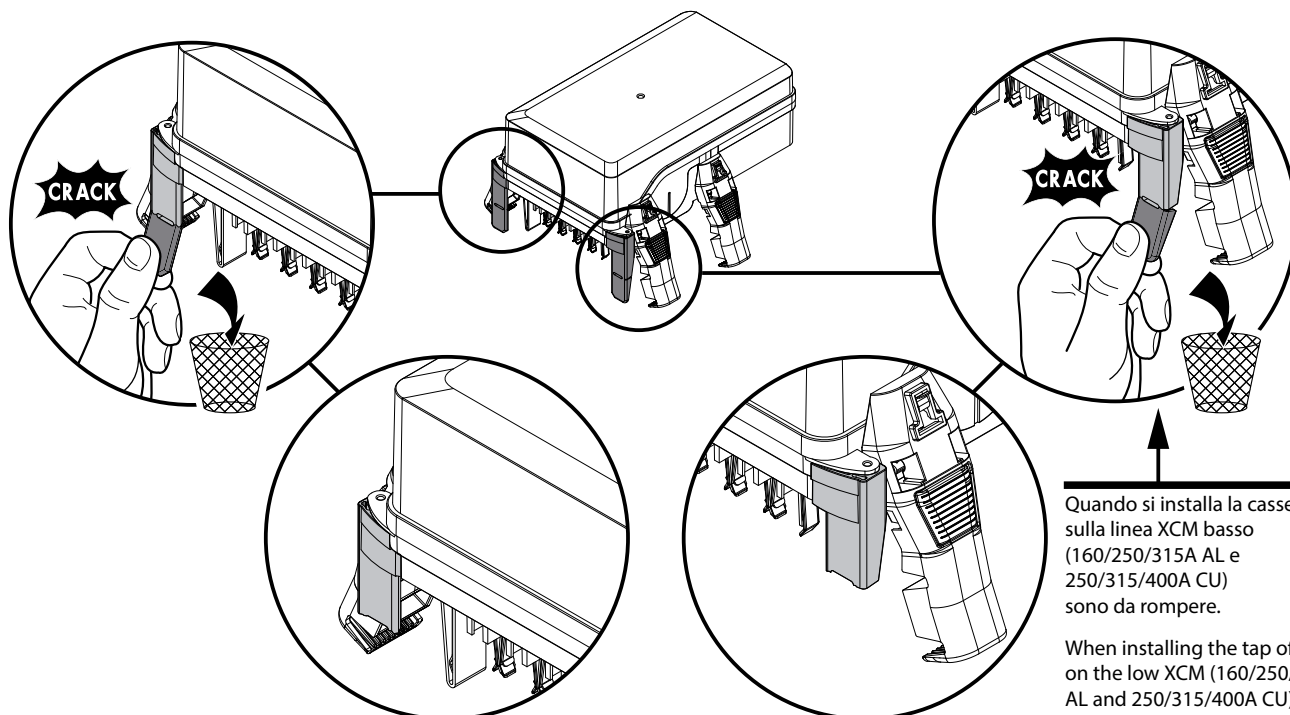
L

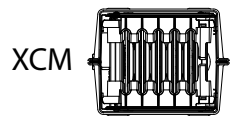


M



*

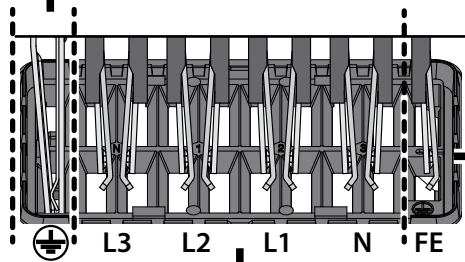
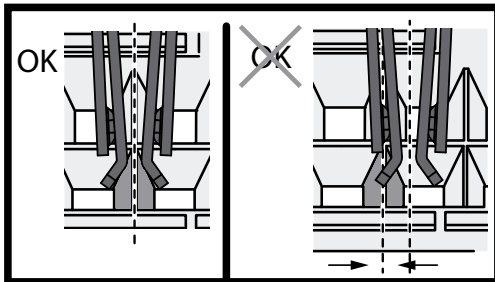
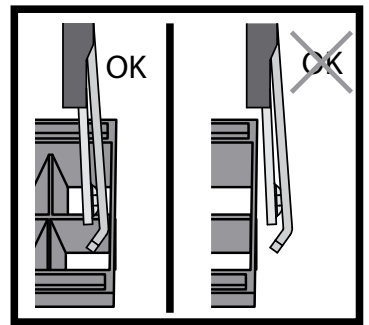




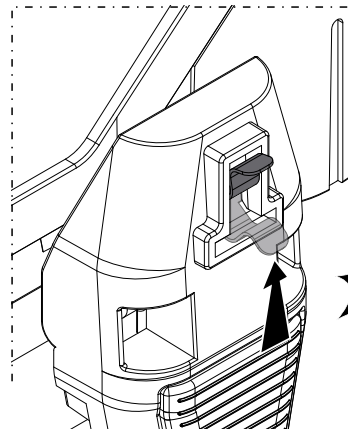
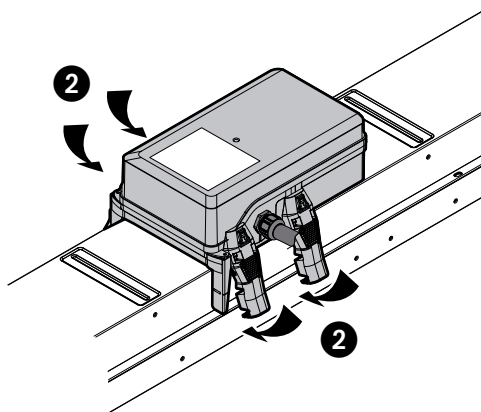
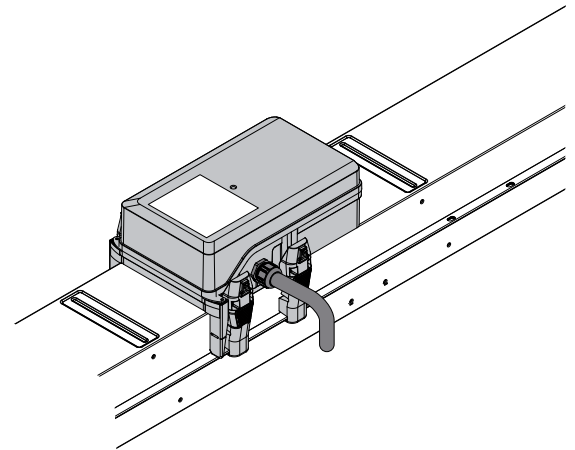
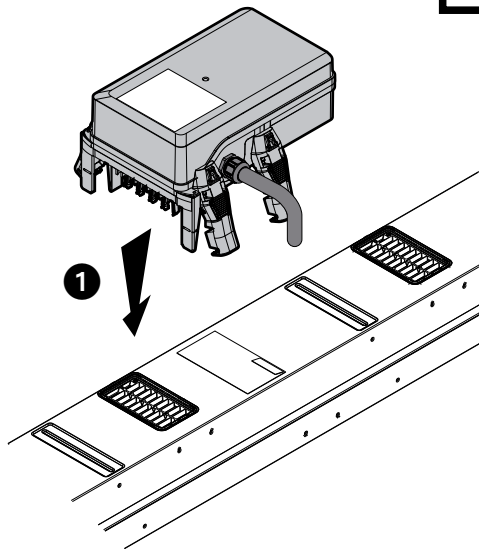
XCM**



PE



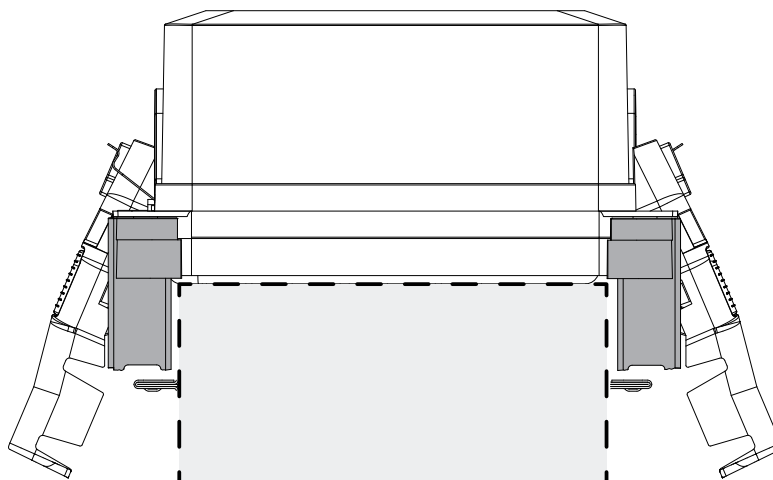
FE



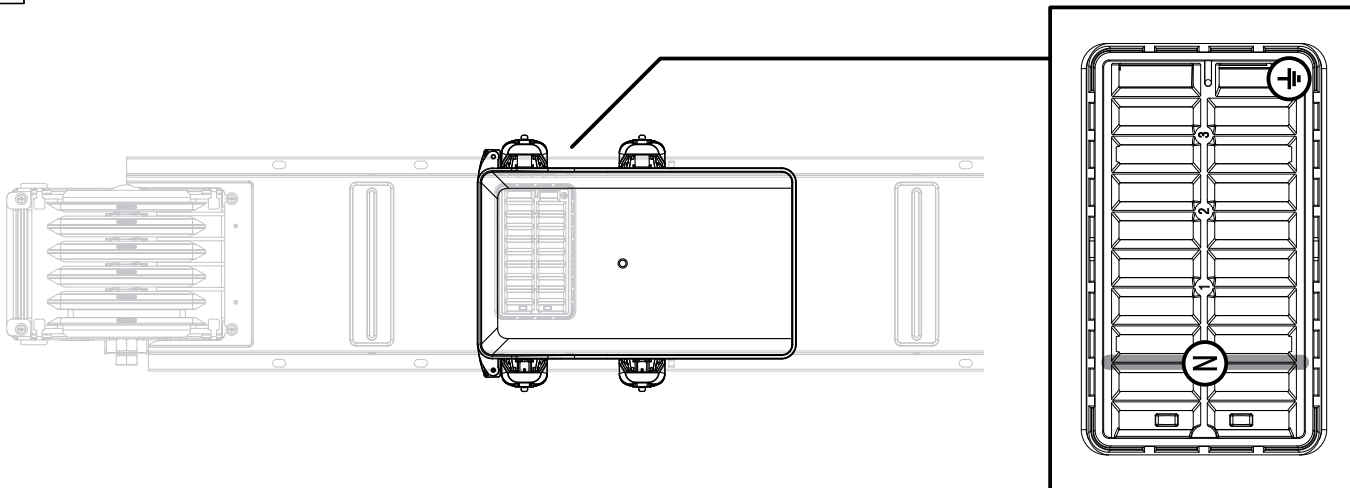
CLICK

3

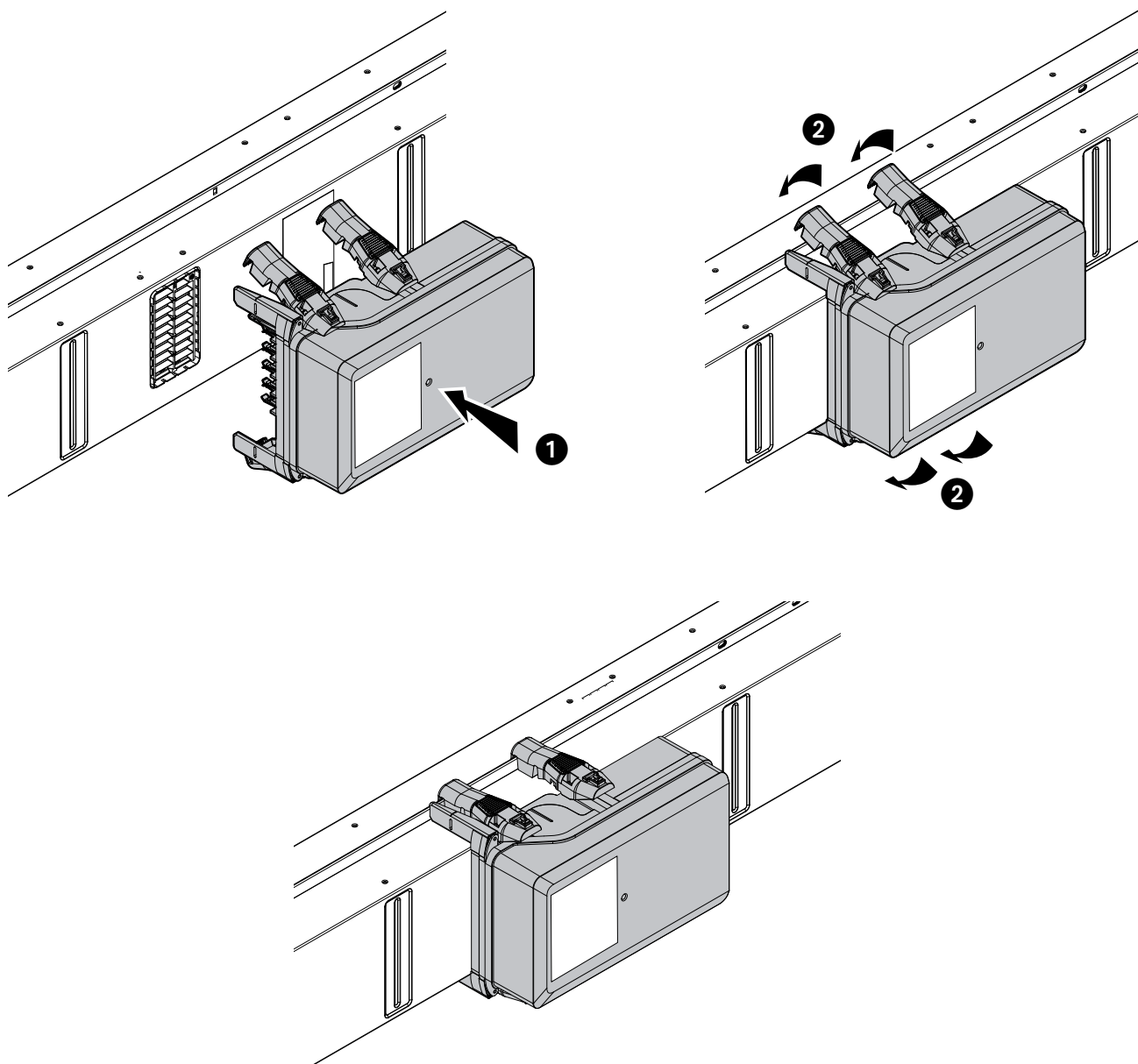
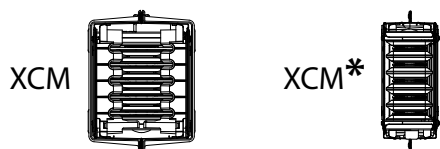
**



O

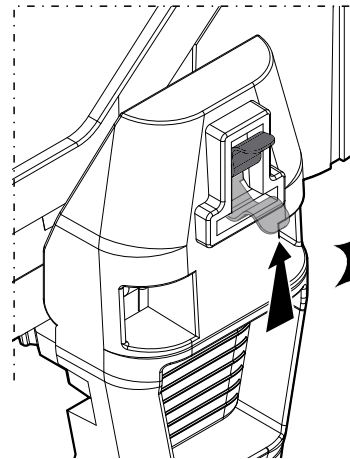
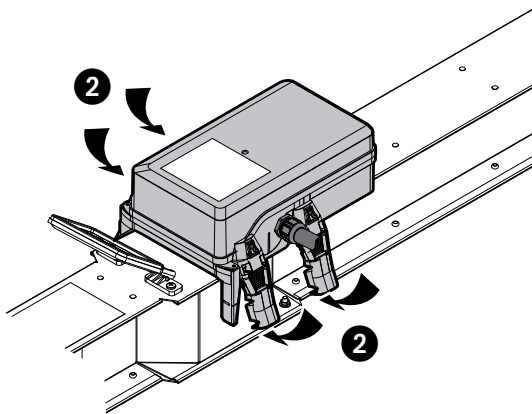
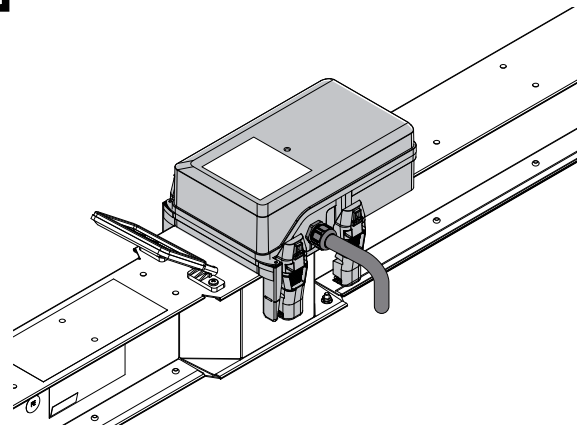
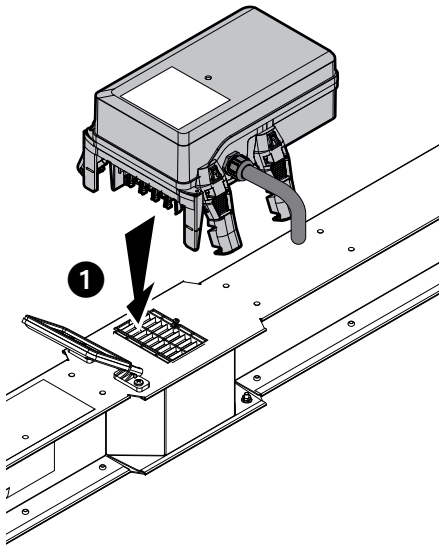
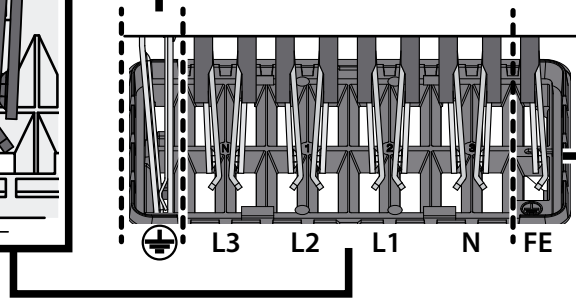
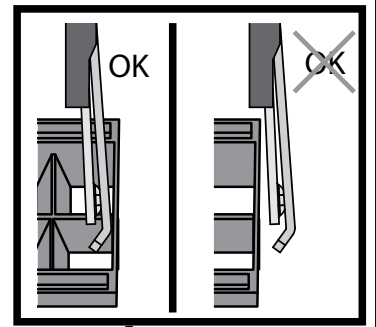
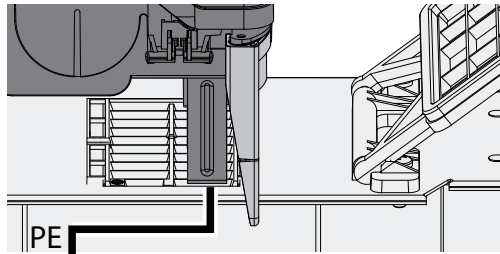
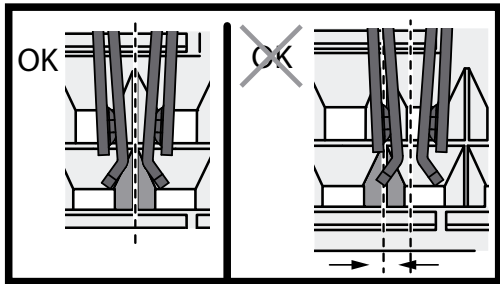


P



Q

XCP



CLICK

R

